

PROTECTION PRODUCTS - EMIClamp[®]

Description

EClamp[®]8052P integrates common mode filtering with low capacitance ESD protection and is designed specifically for MIPI, MHL, and HDMI interfaces. Each device provides filtering and ESD protection for one high-speed differential pair.

EClamp8052P is an easily implemented solution for replacing discrete common mode chokes and ESD protection devices in a single package. These devices utilize silicon avalanche technology for superior ESD and TLP clamping performance. They feature high maximum ESD withstand voltage of +/- 25kV contact, +/-30kV air discharge per IEC 61000-4-2. The integrated common-mode choke has a typical differential mode cutoff frequency >3GHZ and typical common mode suppression of 10dB at 500MHz and 15dB from 1GHz to 2.8GHz. Each channel series resistance is 1.8 Ohms maximum.

EClamp8052P is in a 7-pin SGP1917N5 package, measuring 1.9 x 1.7mm with a nominal height of 0.55mm. The leads have a nominal pin-to-pin pitch of 0.50mm. Flow- through package design simplifies PCB layout and maintains signal integrity on high-speed lines.

Features

- ◆ ESD protection for high-speed data lines to **IEC 61000-4-2 (ESD) ±30kV (air), ±25kV (contact)**
- ◆ **IEC 61000-4-5 (Lightning) 6A (8/20μs)**
- ◆ **IEC 61000-4-4 (EFT) 40A (5/50ns)**
- ◆ Package design optimized for high speed lines
- ◆ ESD protection and common mode filtering for two high-speed lines
- ◆ High differential bandwidth cutoff frequency
- ◆ Qualified to AECQ-100
- ◆ Low ESD clamping voltage
- ◆ Low dynamic resistance: 0.50 Ohms (Typ)
- ◆ Solid-state silicon-avalanche technology

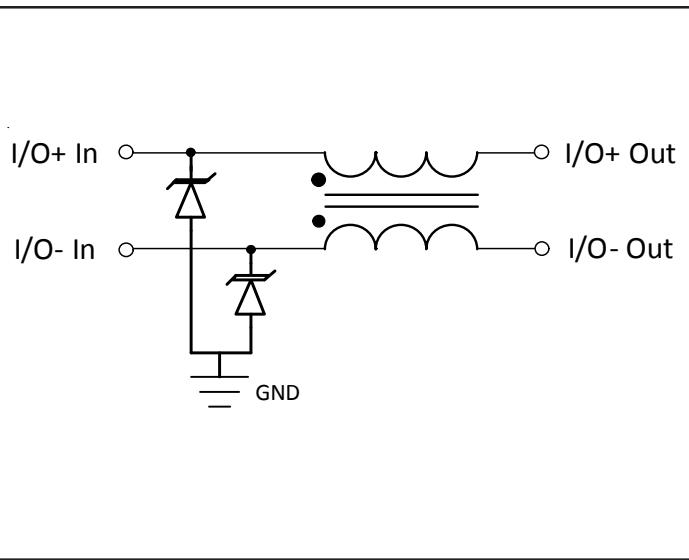
Mechanical Characteristics

- ◆ SGP1917N5 package
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Marking: Marking code + date code
- ◆ Packaging: Tape and Reel

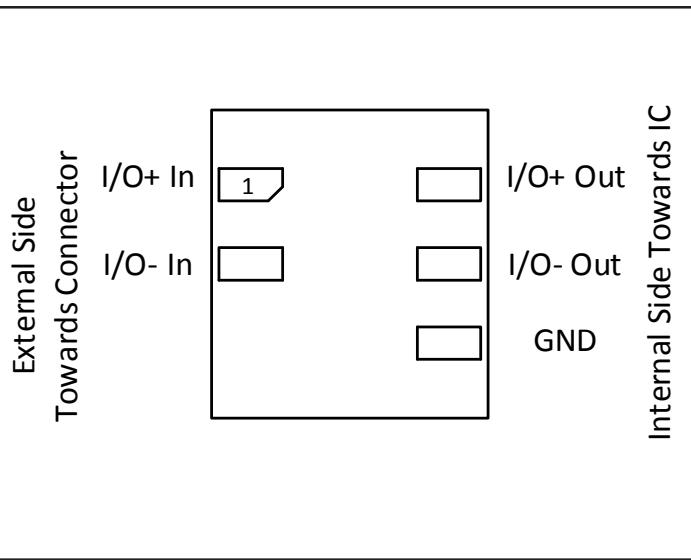
Applications

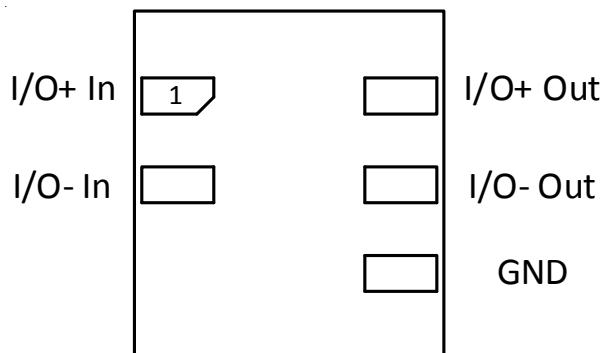
- ◆ MIPI Camera Serial Interface (CSI)
- ◆ MIPI Display Serial Interface (DSI)
- ◆ HDMI Interfaces
- ◆ MHL Interfaces
- ◆ USB 2.0 Interfaces

Circuit Diagram



Pin Configuration (Top View)



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Pin Identification


Pin	Symbol	Identification
1	I/O+ In	Line+ In from Connector (External) Side
2	I/O- In	Line- In from Connector (External) Side
3	GND	Ground
4	I/O- Out	Line- Out to Chip (Internal) Side
5	I/O+ Out	Line+ Out to Chip (Internal) Side

Pin Configuration (Top View)
Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	6	A
ESD per IEC 61000-4-2 (Air) ¹ ESD per IEC 61000-4-2 (Contact) ¹	V_{ESD}	+/- 30 +/- 25	kV
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

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Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}	Pin 1 or Pin 2 to GND			5	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1\text{mA}$, Pin 1 or Pin 2 to GND	6.5	9	11	V
Reverse Leakage Current	I_R	$V_{RWM} = 5.0\text{V}$, Pin 1 or Pin 2 to GND		0.005	0.100	μA
Clamping Voltage	V_c	$I_{PP} = 1\text{A}$, $t_p = 8/20\mu\text{s}$ Pin 1 or Pin 2 to GND			12	V
Clamping Voltage	V_c	$I_{PP} = 6\text{A}$, $t_p = 8/20\mu\text{s}$ Pin 1 or Pin 2 to GND			17	V
ESD Clamping Voltage ²	V_c	$I_{PP} = 4\text{A}$, $t_{lp} = 0.2/100\text{ns}$		11		V
ESD Clamping Voltage ²	V_c	$I_{PP} = 16\text{A}$, $t_{lp} = 0.2/100\text{ns}$		17		V
Dynamic Resistance ³	R_D	$t_p = 100\text{ns}$		0.50		Ohm
Total Channel Capacitance	C_{IN}	$V_R = 0\text{V}$, $f = 1\text{MHz}$, Pin 1 or Pin 2 to GND		0.95	1.2	pF
Differential (SDD21) Cut-Off Frequency	$f_{3\text{dB}}$	50 Ohm Source and Load Termination		3		GHz
Common Mode (SCC21) Attenuation	f_{ATT}	$f=75\text{MHz}$		3		dB
		$f=500\text{MHz}$		10		dB
		$f=1\text{GHz} - 2.8\text{GHz}$		15		dB
Channel Resistance	R_{CH}	Input to Output		1.3	1.8	Ohm

Notes

1)ESD gun return path connected to ESD ground reference plane. ESD discharge between pin 1 and pin 3 or pin 2 and pin 3 with pin 3 connected to ground.

2)Transmission Line Pulse Test (TLP) Settings: $t_p = 100\text{ns}$, $t_r = 0.2\text{ns}$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70\text{ns}$ to $t_2 = 90\text{ns}$.

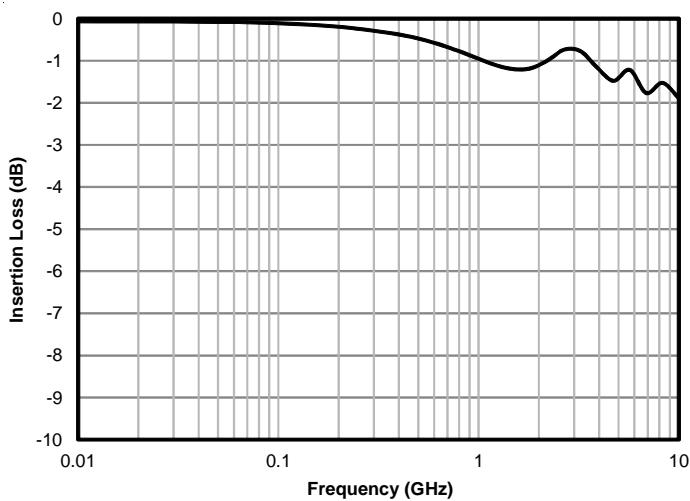
3) Dynamic resistance calculated from $I_{pp} = 4\text{A}$ to $I_{pp} = 16\text{A}$



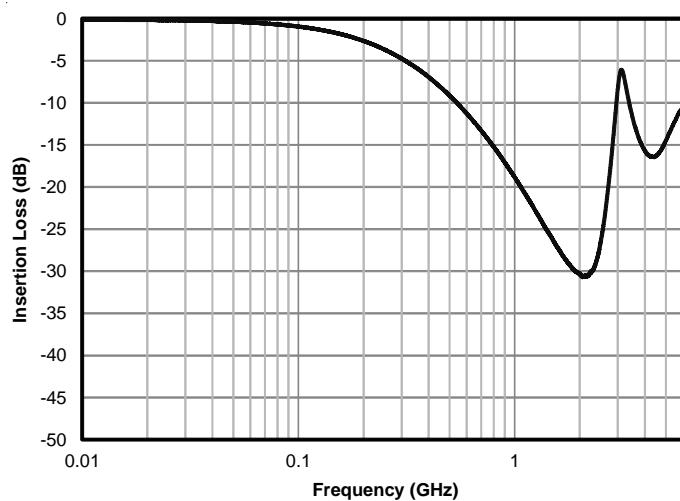
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Typical Characteristics

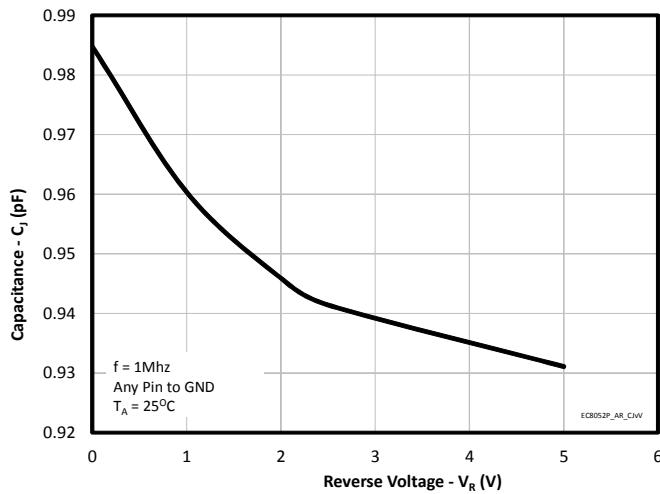
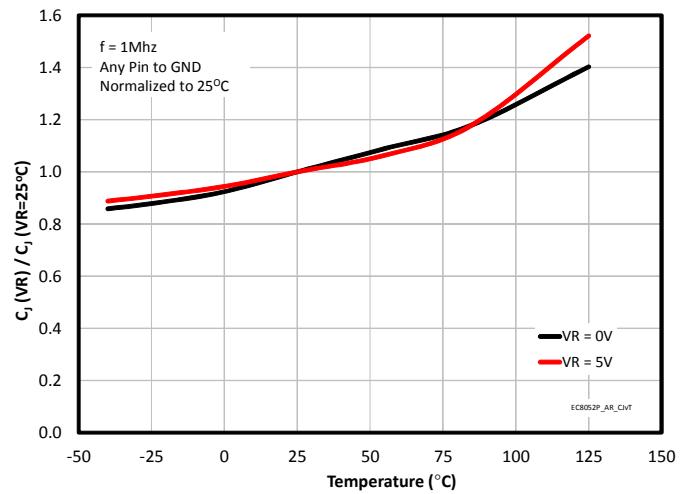
Differential Mode Attenuation vs. Frequency



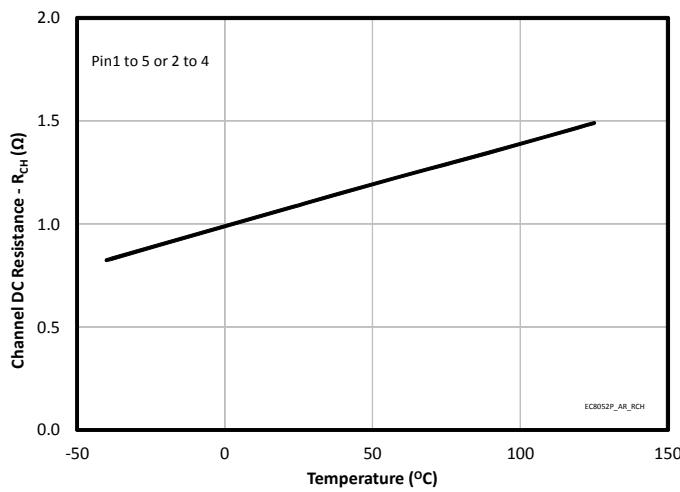
Common Mode Attenuation vs. Frequency



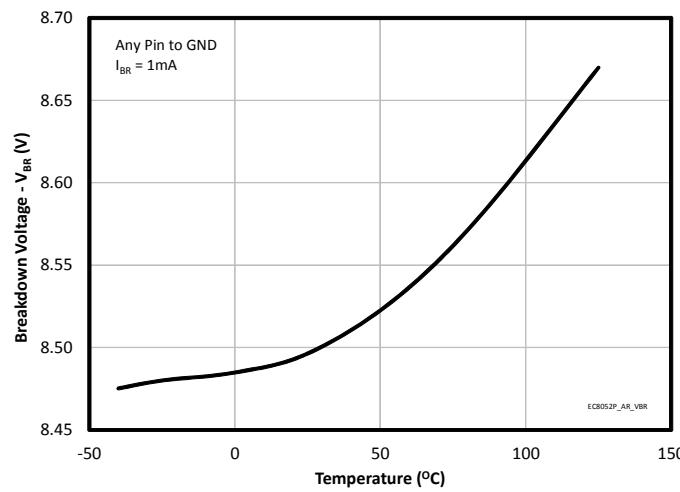
Junction Capacitance vs. Reverse Voltage

Junction Capacitance vs. Temperature
(Normalized to $T=25^\circ\text{C}$)

Channel DC Resistance vs. Temperature



Breakdown Voltage (VBR) vs. Temperature





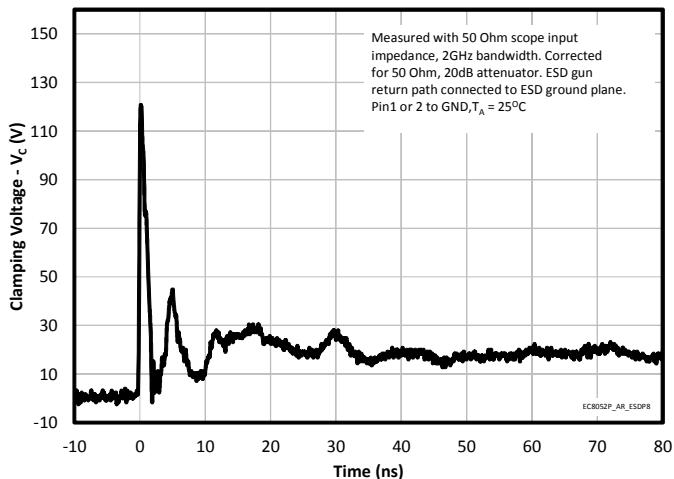
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EClamp8052P

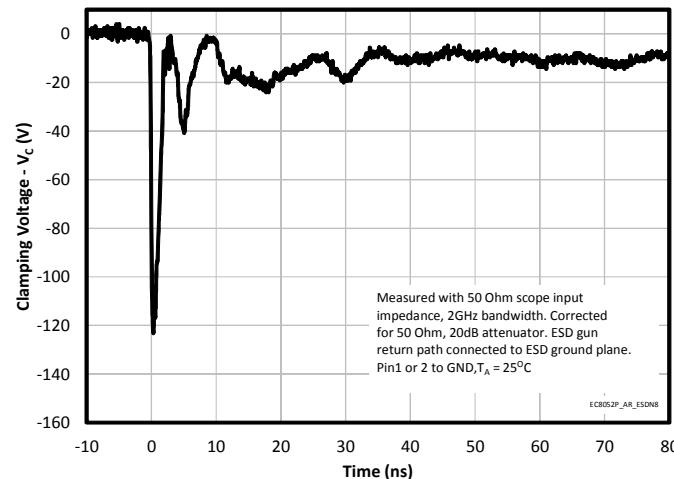
PROTECTION PRODUCTS

Typical Characteristics

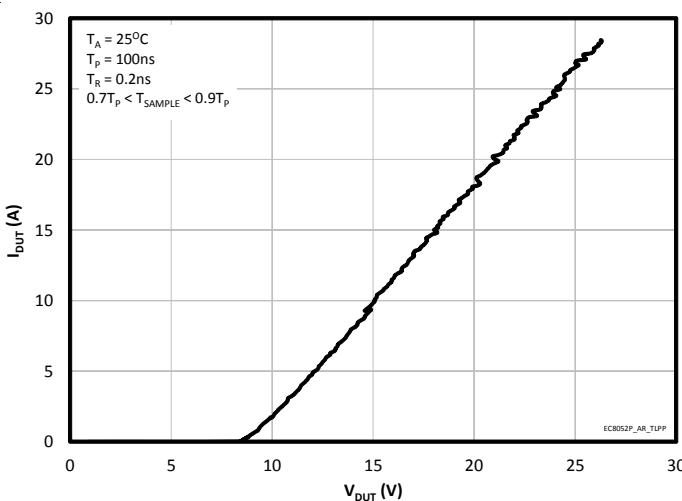
ESD Clamping (+8kV Contact per IEC 61000-4-2)



ESD Clamping (-8kV Contact per IEC 61000-4-2)

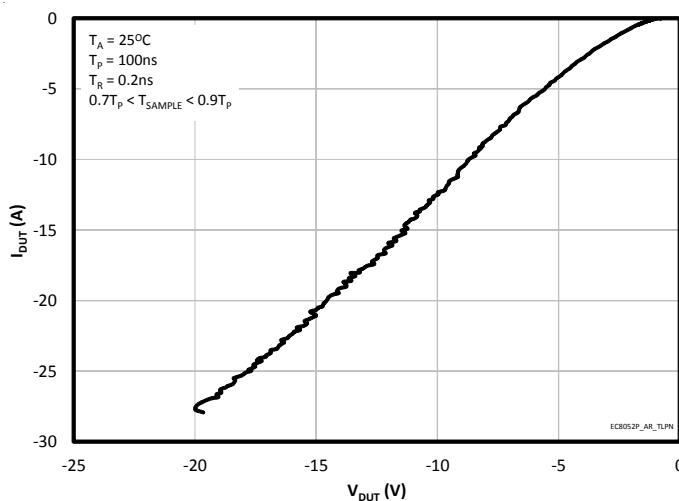


TLP Characteristic (Positive)

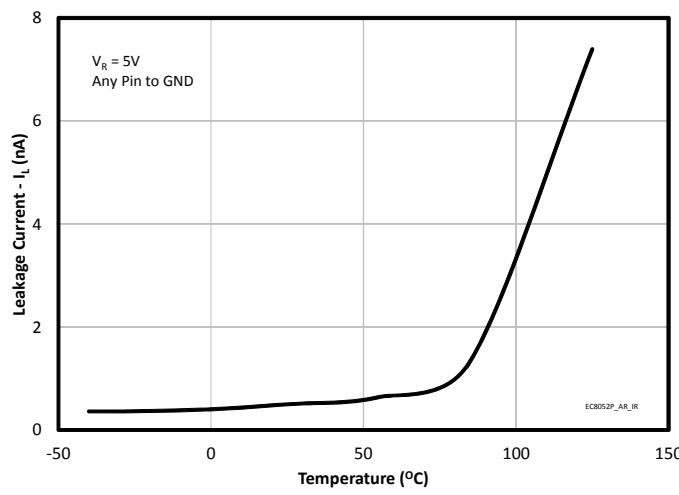
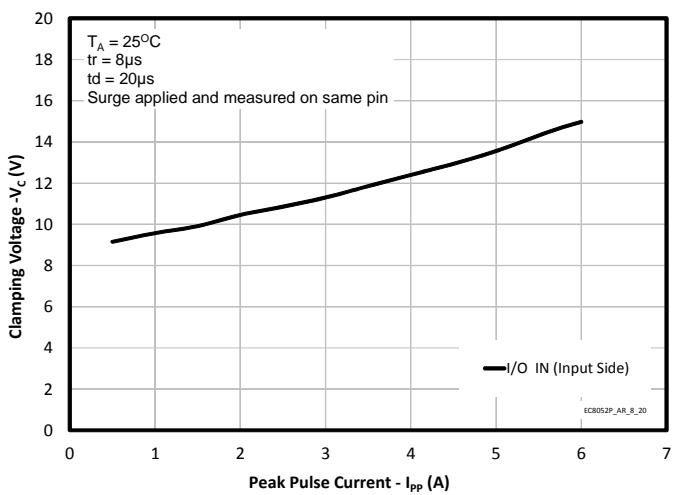


Clamping Voltage vs. Peak Pulse Current ($t_p=8/20\mu\text{s}$)

TLP Characteristic (Negative)



Reverse Leakage vs. Temperature





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Application Examples

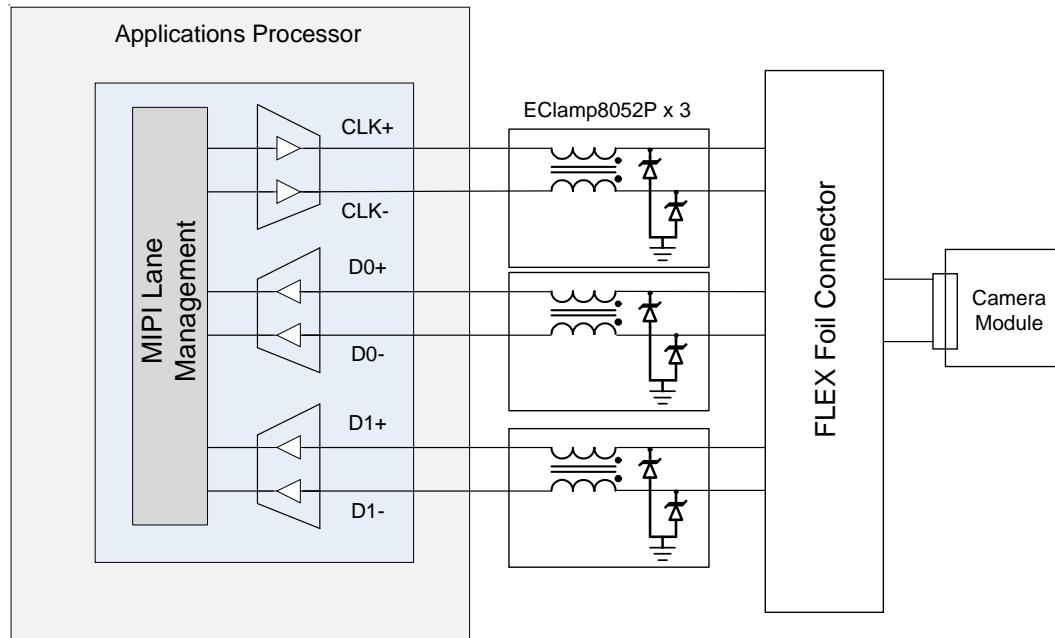


Figure 1 - MIPI Camera Serial Interface Protection

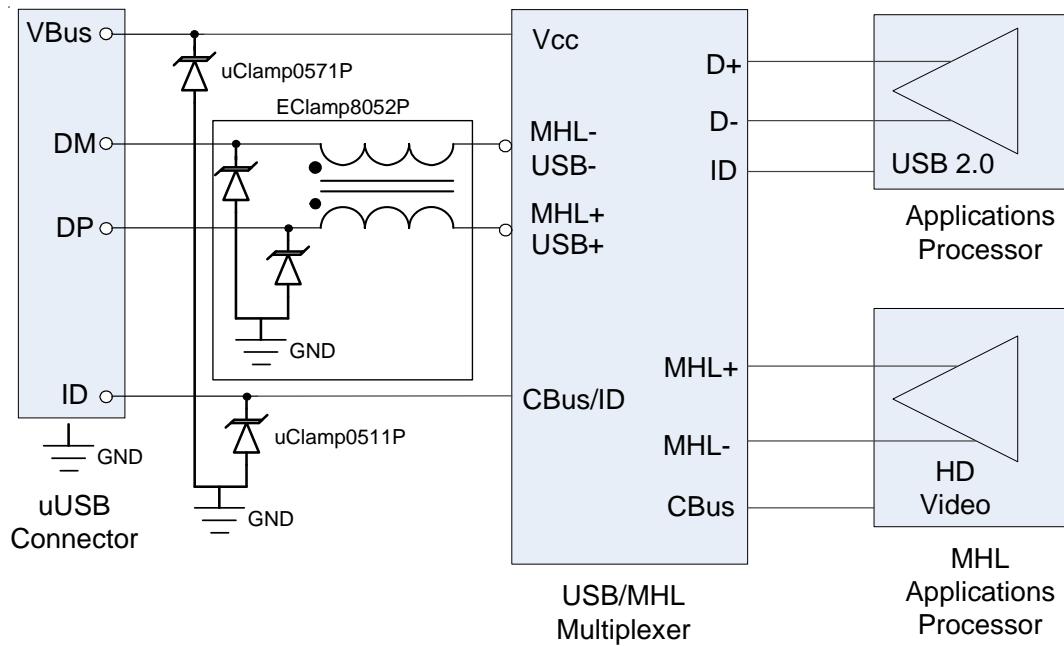
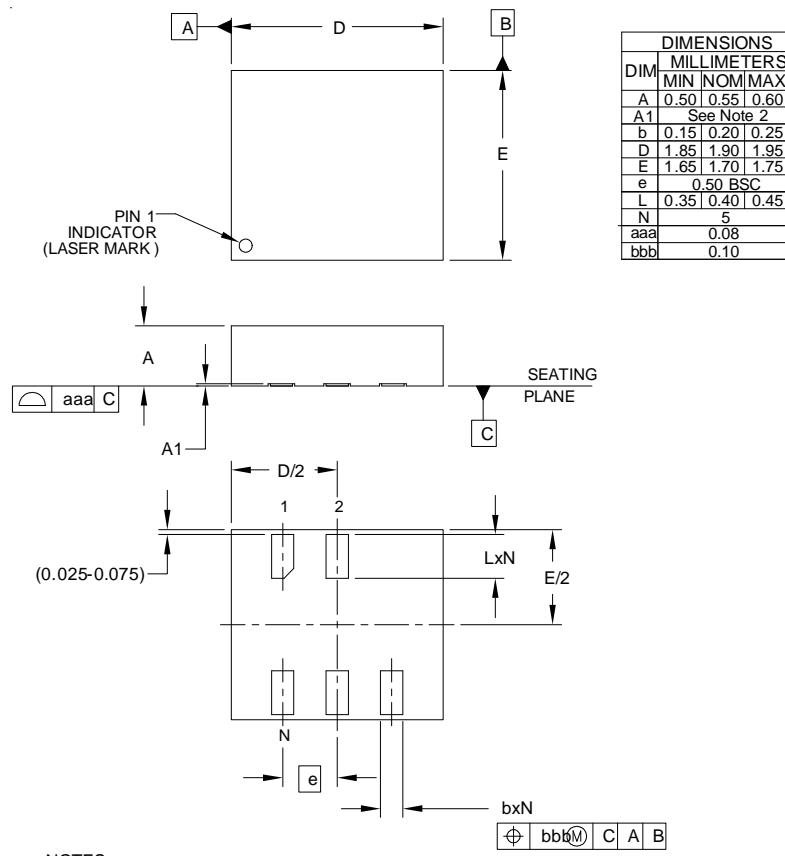


Figure 2 - MHL/USB2.0 Interface Protection



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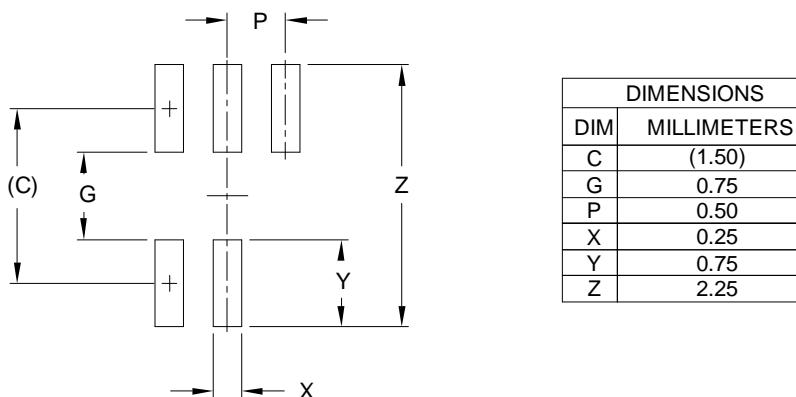
Outline Drawing - SGP1917N5



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. A1 BOTTOM SOLDER MASK (0.020+/-0.007)
SOLDER PAD (0.018+/-0.005)

Land Pattern - SGP1917N5



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

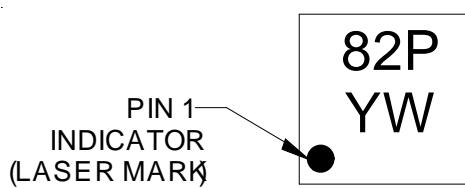


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Marking Codes



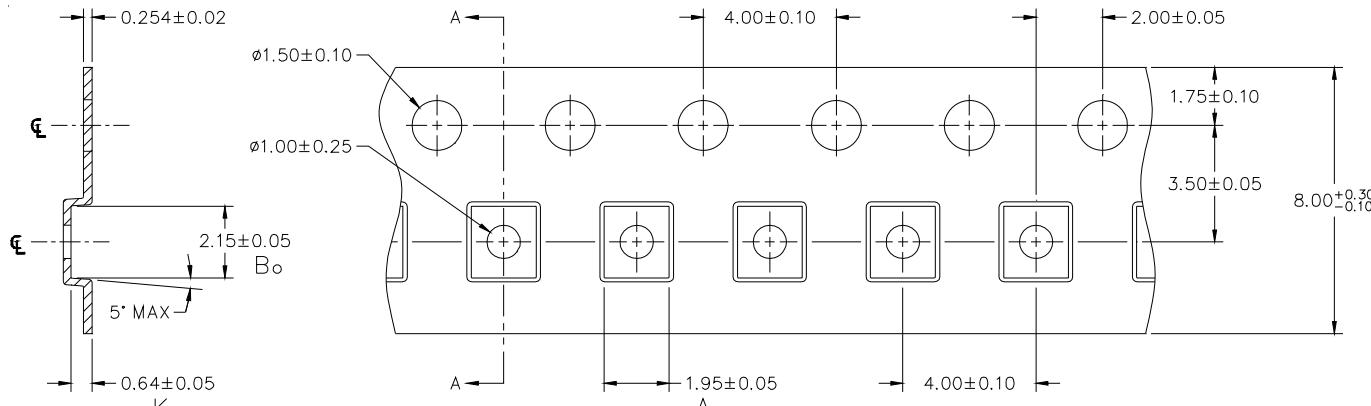
YW = Alphanumeric character Date Code

Ordering Information

Part Number	Qty per Reel	Reel Size
EClamp8052P.TCT	3,000	7 Inch

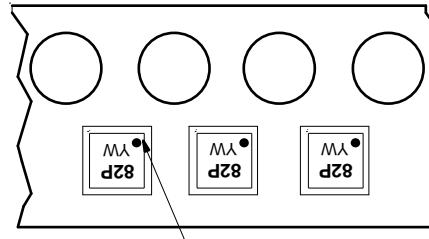
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Carrier Tape Specification



SECTION A-A

NOTE: ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



Pin 1 Location
(Towards Sprocket Holes)

Device Orientation in Tape

Contact Information

Semtech Corporation
Protection Products Division
200 Flynn Road, Camarillo, CA 93012
Phone: (805)498-2111 FAX (805)498-3804